

HOSTAFORM® S 9362

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Hostaform® acetal copolymer grade S 9362 is an impact modified grade for applications requiring improved impact. Hostaform® S 9362 provides good impact strength while improving modulus and weld line strength over standard impact modified grades. Chemical abbreviation according to ISO 1043-1: POM-HI

Product information

Resin Identification	POM	ISO 1043
Part Marking Code	>POM<	ISO 11469

Rheological properties

Melt volume-flow rate	6.5 cm ³ /10min	ISO 1133
Temperature	190 °C	
Load	2.16 kg	
Moulding shrinkage, parallel	1.9 %	ISO 294-4, 2577
Moulding shrinkage, normal	1.8 %	ISO 294-4, 2577

Typical mechanical properties

Tensile modulus	2300 MPa	ISO 527-1/-2
Tensile stress at yield, 50mm/min	55 MPa	ISO 527-1/-2
Tensile strain at yield, 50mm/min	10 %	ISO 527-1/-2
Flexural modulus	2200 MPa	ISO 178
Charpy impact strength, 23°C	N kJ/m ²	ISO 179/1eU
Charpy impact strength, -30°C	190 kJ/m ²	ISO 179/1eU
Charpy notched impact strength, 23°C	10 kJ/m ²	ISO 179/1eA
Charpy notched impact strength, -30°C	6 kJ/m ²	ISO 179/1eA
Izod notched impact strength, 23°C	10 kJ/m ²	ISO 180/1A
Izod notched impact strength, -40°C	6.0 kJ/m ²	ISO 180/1A
Hardness, Rockwell, M-scale	75	ISO 2039-2
Poisson's ratio	0.39 ^[C]	

[C]: Calculated

Thermal properties

Melting temperature, 10°C/min	165 °C	ISO 11357-1/-3
Temperature of deflection under load, 1.8 MPa	87 °C	ISO 75-1/-2
Temperature of deflection under load, 0.45 MPa	151 °C	ISO 75-1/-2
Coefficient of linear thermal expansion (CLTE), parallel	110 E-6/K	ISO 11359-1/-2
Coefficient of linear thermal expansion (CLTE), normal	110 E-6/K	ISO 11359-1/-2

Physical/Other properties

Humidity absorption, 2mm	0.25 %	Sim. to ISO 62
Water absorption, 2mm	0.8 %	Sim. to ISO 62
Density	1390 kg/m ³	ISO 1183

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Injection

Drying Recommended	no
Drying Temperature	100 °C
Drying Time, Dehumidified Dryer	3 - 4 h
Processing Moisture Content	≤0.2 %
Melt Temperature Optimum	195 °C
Min. melt temperature	180 °C
Max. melt temperature	210 °C
Screw tangential speed	≤0.3 m/s
Mold Temperature Optimum	100 °C
Min. mould temperature	80 °C
Max. mould temperature	120 °C
Hold pressure range	60 - 120 MPa
Back pressure	2 MPa
Ejection temperature	133 °C

Characteristics

Processing	Injection Moulding, Extrusion
Delivery form	Pellets
Additives	Release agent
Special characteristics	High impact or impact modified

Additional information

Processing Notes

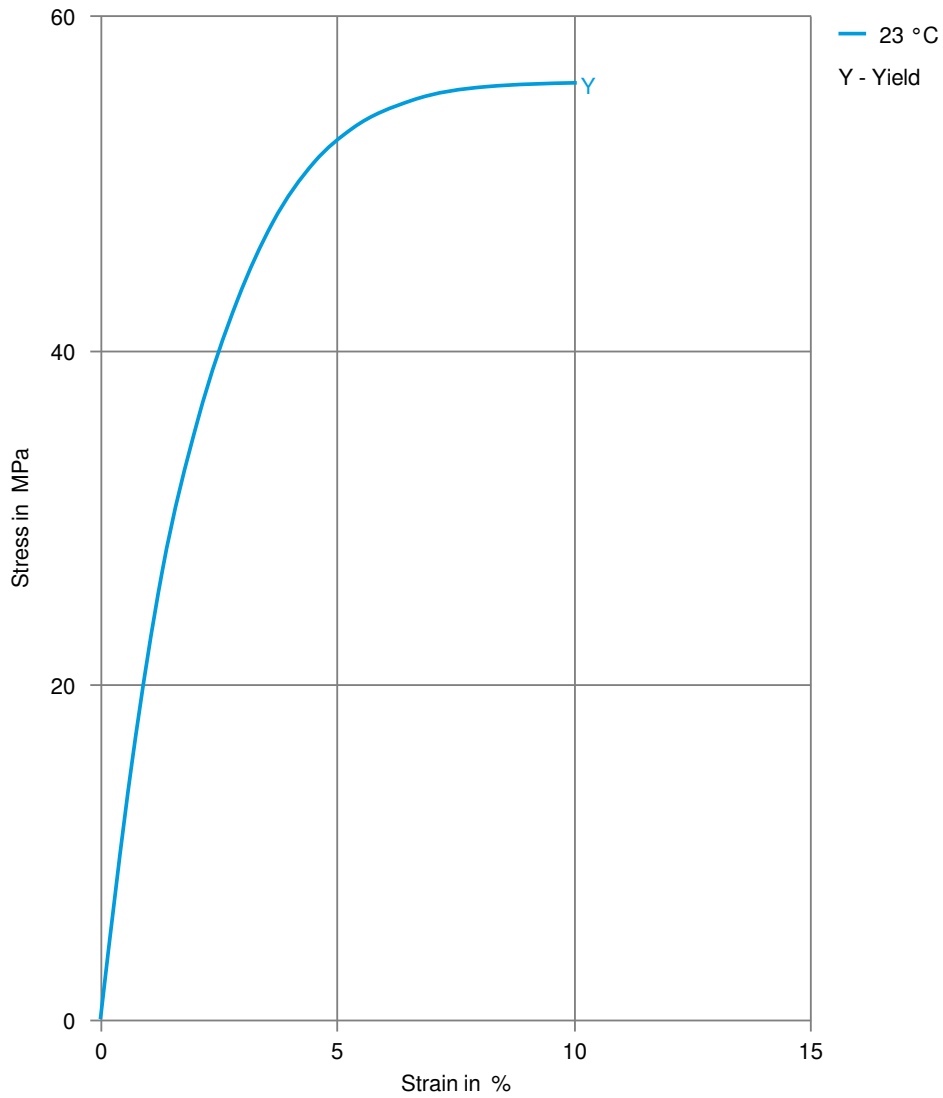
Pre-Drying

Drying is not normally required. If material has contacted moisture through improper storage and handling or through regrind use, dry to prevent splay and odor problems.

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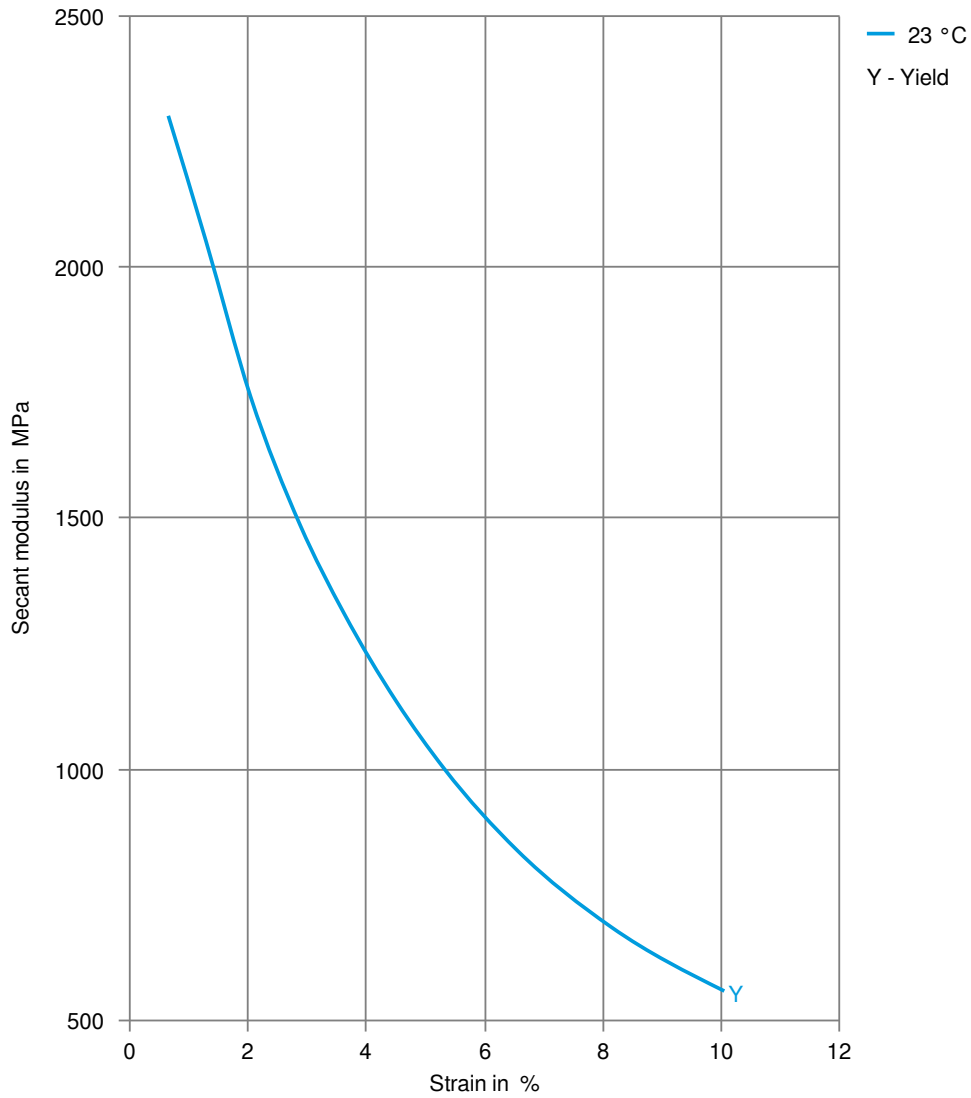
Stress-strain



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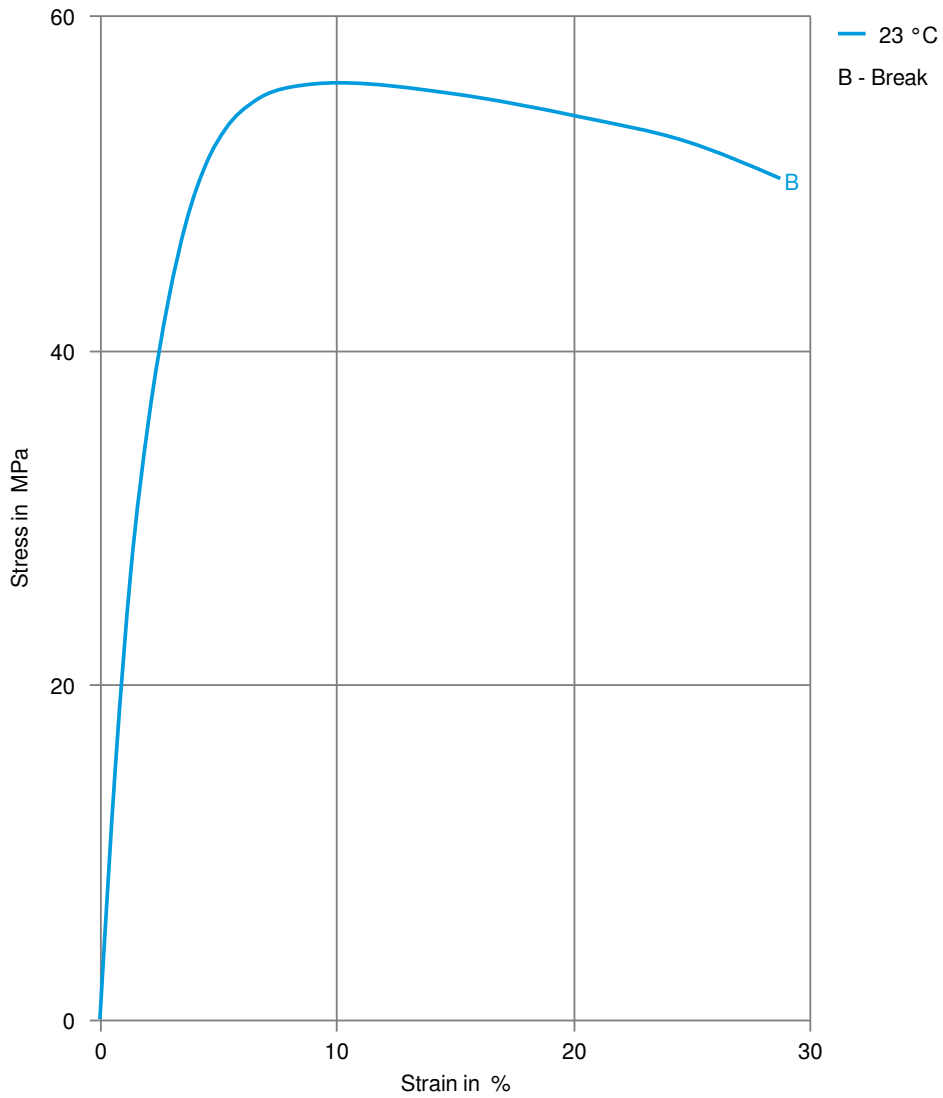
Secant modulus-strain



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Stress-strain, 50mm/min



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Secant modulus-strain, 50mm/min

